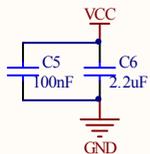
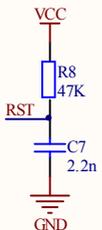
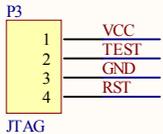


v1.0 -> v1.1

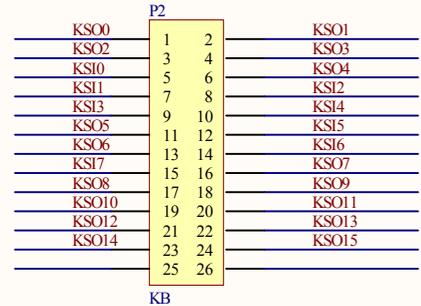
1. Removes KEY net on P3.0
2. Removes R7 and add a test point on P2.6



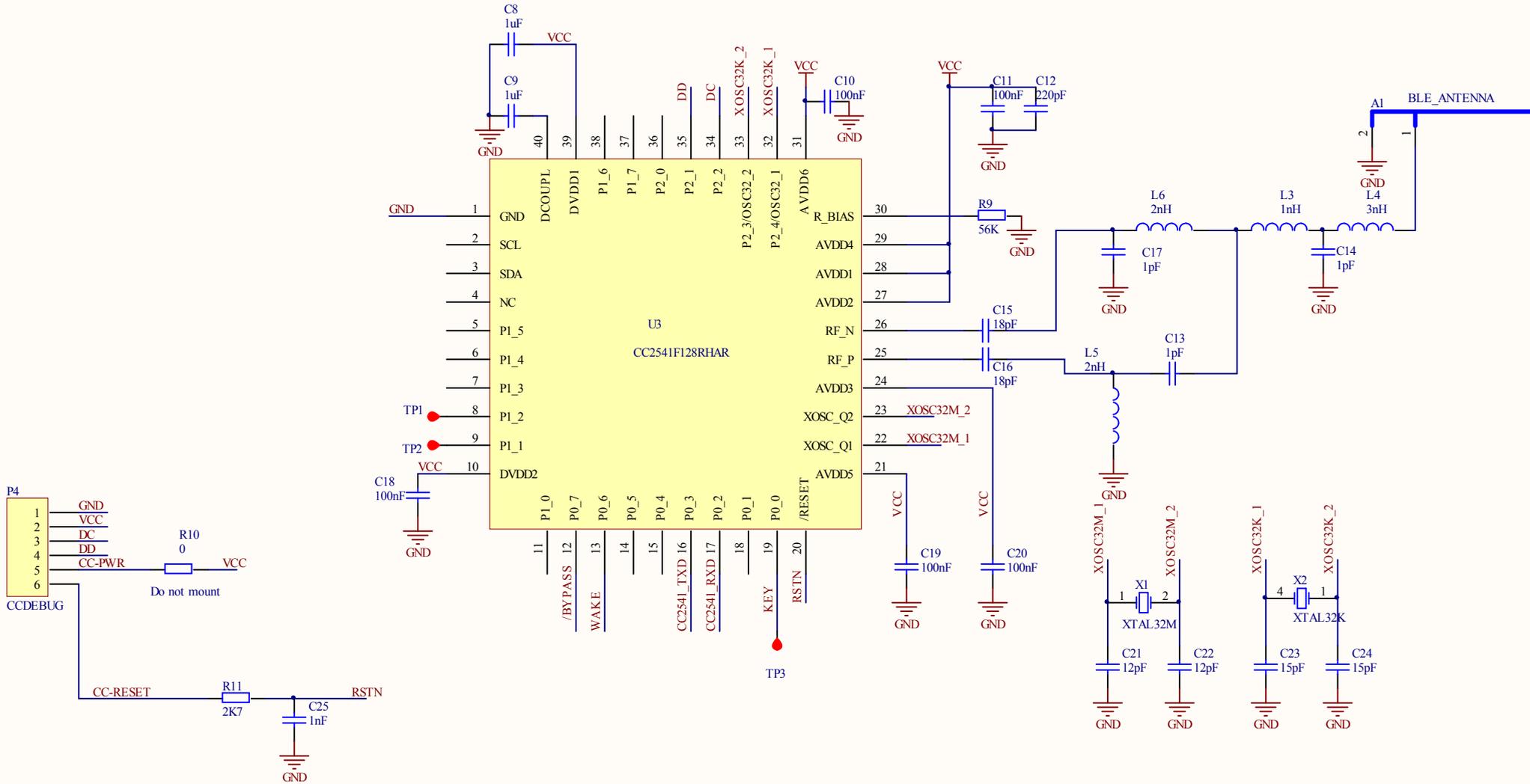
WAKE TP4

GND	1	DVSS	P2.5	40	KSO13
BAT_DET	2	P2.7 /XOUT	DVCC	39	VCC
	3	P2.6 /XIN	DVCC	38	
GND	4	DVSS	TEST/SBWTCK	37	TEST
RST	5	/RST/SWTDIO	P1.7	36	KSI7
KSO8	6	P2.0/A0	P1.6	35	KSI6
KSO9	7	P2.1/A1	P1.5	34	KSI5
BAT_LVL	8	P2.2/A2	P1.4	33	KSI4
	9	P2.0/A0	P1.3	32	KSI3
LED_GREEN	10	SDA/P3.1	P1.2	31	KSI2
LED_RED	11	SCL/P3.2	P1.1	30	KSI1
KSO10	12	P3.3	P1.0	29	KSI0
GND	13	P3.3	P1.0	28	KSO12
VCC	14	AVSS	P2.4	27	KSO11
KSO0	15	AVCC	P2.3	26	KSO15
KSO1	16	P4.0 /TB0	A7/P3.7	25	KSO14
KSO2	17	P4.1 /TB1	A6/P3.6	24	CC2541_TXD
KSO3	18	P4.2 /TB2	RXD/SOMI/P3.5	23	CC2541_RXD
KSO4	19	P4.3 /A12	TXD/SIMO/P3.4	22	KSO7
KSO5	20	P4.4 /A13	P4.7	21	KSO6
		P4.5 /A14	A15/P4.6		

MSP430G2544IRHA40



Title		
CC2541 BLE keyboard		
Size	Number	Revision
A4		v1.1
Date:	2014-8-19	Sheet 1 of 2
File:	Z:\shared\brkbref\BTKBREF_rev1_1.SchDoc	Drawn By:



Title		
CC2541 BLE keyboard		
Size	Number	Revision
A4		v1.1
Date:	2014-8-19	Sheet 2 of 2
File:	Z:\shared\brkbref\cc2541_rev1_1.SchDoc	Drawn By:

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